











#### Main Features

- Intel Atom® x7000RE/E/C processor
- 1 x SO-DIMM slot for DDR5, 4800 MT/s , ECC/non-ECC, up to 16 GB
- eMMC 32GB onboard
- 4 x 2.5GbE RJ45 ports
  - 2 x PoE+ ports, supports up to 30W (802.3at) (optional)
- 1 x 1GbE management port
- 2 x M.2 3042/3052 for LTE/5G FR1 modules
- 1 x mini-PCIe for AI card or Wi-Fi module
- 1 x M.2 2242 SATA SSD
- TPM 2.0 onboard

## **Product Overview**

DNA 140 is NEXCOM's latest Al-in-a-Box network appliance, built on the newest Intel Atom® processors x7000RE/E/C Series. It features four 2.5GbE LAN ports to fulfill the demand for multi-media or small-to-mid business data transmission. DNA 140 is a compact yet powerful device, a game-changer offering a robust foundation for Al-driven applications, fast and secure data transfer, and efficient edge computing. Its adaptability and feature-rich design make it an ideal choice for businesses to seamlessly integrate Al capabilities into 5G, SD-WAN, SASE, and Edge computing fields.

## **Specifications**

#### Main Board

- Intel Atom® x7433RE CPU, 4 cores
  - Compatible with Intel Atom® x7000RE/C (formerly Amston Lake) and x7000E (formerly Alder Lake-N) CPU, up to 8 cores, 12W
- TPM 2.0 onboard

#### Main Memory

+  $1\,\mathrm{x}$  SO-DIMM slot for DDR5, 4800 MT/s , ECC/non-ECC, up to 16 GB

#### Storage Device

- eMMC 32GB onboard
- 1 x M.2 2242 for SATA SSD

#### Interface External

- Button: Power/Reset/NEXBOOT
- LED: PWR/Sys/Storage/NEXBOOT/LAN/MGNT
- 1 x USB 3.0 port
- 1 x RJ45 console port
- 4 x 2.5GbE RJ45 ports
  - 2 x PoE+ ports, supports up to 30W (802.3at) (optional)
- 1 x 1GbE management port
- 2 x SIM slots
- 10 x Antenna holes (8 x antennas for 5G/LTE, 2 x antennas for Wi-Fi)

### Interface Internal

- 1 x M.2 3052 Key B slot for LTE/5G FR1 module
- +  $1 \times M.2 3042/3052$  Key B slot for LTE/5G FR1 module
- 1 x mini-PCIe slot for AI card or Wi-Fi module
- 1 x M.2 2242 Key M slot for SATA SSD

#### Power

- 1 x 65W 12V DC-in power adapter
- 72W 54W DC-in power adapter for PoE (optional)

#### **Dimensions and Weight**

- Chassis dimension: 255 x 150 x 44 mm
- Carton dimension: 343 x 258 x 212 mm
- Without packing: 1.5 kg
- With packing: 2.5 kg

## Environment

- Operating temperature: 0°C~40°C
- Storage temperature: -20°C~80°C
- Relative humidity: 10%~90% non-condensing

#### Certifications

• CE/FCC Class B (without Wi-Fi, 5G modules)

# Ordering Information

 DNA 140 (P/N: 10L00014000X0)
Intel Atom® x7433RE processor, 4 cores, 4 x 2.5GbE RJ45 ports, 1 x 65W 12V DC-in power adapter

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